



U.S. :

07-23-1998

ICE

Case Docket No. 980575**100771672**DEPARTMENT OF COMMERCE
Patent and Trademark OfficeRECORDATION FORM COVER SHEET
PATENTS ONLYTo the Assistant Commissioner for Patents.
Please record the attached original documents or copy thereof.

1. Name of conveying parties:

Takaaki IZAWA and Tsuyoshi UCHIKURA

Additional name(s) of conveying party(ies) attached? Yes No XX

2. Name and address of receiving party:

Name: YAZAKI CORPORATION

Street Address:

4-28, Mita 1-chome,
Minato-ku, TOKYO 108-0073, JapanAdditional name(s) & address(es) attached? Yes No XX3. Nature of conveyance: **Assignment**Execution Date: **June 8, 1998**

4. Title:

OVERHEAT PROTECTION DEVICE, SEMICONDUCTOR SWITCH APPARATUS
USING THE SAME, AND INTELLIGENT POWER MODULE

5. Application number(s) or patent number(s): 09/066,529

If this document is being filed together with a new application, the execution date of
the application is: _

07/22/1998 DWG JYEN 00000096 09066529

01 FC:581

40.00 OP

Additional numbers attached? Yes No XX

6. Name and address of party to whom correspondence concerning document should be mailed:

Name: Armstrong, Westerman, Hattori,
McLeland & Naughton
Suite 1000
1725 K Street, N.W.
Washington, D.C. 20006

7. Total number of applications and patents involved: 1

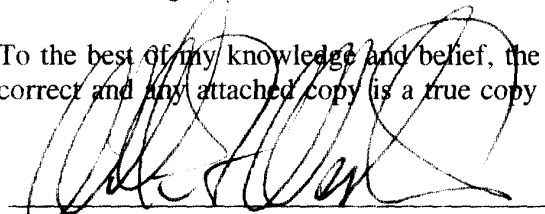
8. Total fee (37 CFR 3.41). \$ **40.00**

XX Check enclosed

9. Deposit Account No.: **01-2340**

10. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.



William F. Westerman
Reg. No.: 29,988

Date July 20, 1998

Total number of pages including cover sheet: 3

WFW/tmb

U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) hereinafter ASSIGNOR) by

(Insert ASSIGNEE's
Name(s) Address(es))

Yazaki Corporation
4-28, Mita 1-chome, Minato-ku, TOKYO, 108-0073, Japan

(hereinafter ASSIGNEE), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled OVERHEAT PROTECTION DEVICE, SEMICONDUCTOR SWITCH APPARATUS USING THE SAME, AND INTELLIGENT POWER

(Title of Invention)

MODULE

(*If the assignment is being filed after the filing of the application, this section must be completed)

for which application for Letters Patent of the United States was executed on even date herewith unless otherwise indicated below:

filed on April 27, 1998 Serial No. 09/066,529
(Armstrong, Westerman, Hattori, McLeland & Naughton is hereby authorized to insert the series code, serial number and/or filing date hereon, when known)

and all Letters Patent of the United States to be obtained therefor on said application or any continuation, divisional, substitute, reissue or reexamination thereof for the full term or terms for which the same may be granted.

The ASSIGNOR agrees to execute all papers necessary in connection with the application and any continuation, divisional, reissue or reexamination applications thereof and also to execute separate assignments in connection with such applications as the ASSIGNEE may deem necessary or expedient.

The ASSIGNOR agrees to execute all papers necessary in connection with any interference litigation, or other legal proceeding which may be declared concerning this application or any continuation, divisional, reissue or reexamination thereof or Letters Patent or reissue patent issued thereon and to cooperate with the ASSIGNEE in every way possible in obtaining and producing evidence and proceeding with such interference, litigation, or other legal proceeding.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

(Signatures)

Takaaki Izawa Takaaki IZAWA June 8, 1998
(SIGNATURE) (TYPE NAME) (DATE)

Tsuyoshi Uchikura Tsuyoshi UCHIKURA June 8, 1998
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